CLEAN COPY OF THE AMENDED CLAIMS

3. (Amended) A method of cutting CSP substrates comprising the steps of:

mounting plural CSP substrates on a single frame without overlapping them one upon the other, each CSP substrate having CSPs formed on plural rectangular regions thereof sectioned by cutting streets arranged in a form of a lattice;

recognizing a mounting position of each of said CSP substrates on said frame and storing the mounting positions in a storage means;

securing said frame mounting said plural CSP substrates onto a chuck;

imaging a surface of each of said CSP substrates by a precision imaging means, recognizing the positions of said cutting streets of each of said CSP substrates on said frame secured onto said chuck by analyzing the obtained image, and storing a position of each of said cutting streets in said storage means;

positioning said chuck, to which said frame is secured, relative to each other with respect to said precision imaging means based on the stored mounting position of each of said CSP substrates on said frame at a time of imaging the surface of each of said CSP substrates by said precision imaging means; and

cutting each of said CSP substrates along said cutting streets by moving said chuck and a cutting means relatively to each other based on the stored position of said cutting streets of each of said CSP substrates, wherein

said frame has an opening at a central portion thereof, a mounting tape extending across said opening is stuck onto a back surface of said frame, and said CSP substrates are each stuck onto said mounting tape so as to be positioned in said opening of said frame, and

said mounting tape has plural mounting position indications for indicating the mounting position of each of said CSP substrates, and the mounting position of each of

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said CSP substrates on said frame is recognized by viewing by eyes said mounting position indications and is manually input to said storage means.

4. (Amended) A method of cutting CSP substrates comprising the steps of:

mounting plural CSP substrates on a single frame without overlapping them one upon the other, each CSP substrate having CSPs formed on plural rectangular regions thereof sectioned by cutting streets arranged in a form of a lattice;

recognizing a mounting position of each of said CSP substrates on said frame and storing the mounting positions in a storage means;

securing said frame mounting said plural CSP substrates onto a chuck;

imaging a surface of each of said CSP substrates by a precision imaging means, recognizing the positions of said cutting streets of each of said CSP substrates on said frame secured onto said chuck by analyzing the obtained image, and storing a position of each of said cutting streets in said storage means;

positioning said chuck, to which said frame is secured, relative to each other with respect to said precision imaging means based on the stored mounting position of each of said CSP substrates on said frame at a time of imaging the surface of each of said CSP substrates by said precision imaging means; and

cutting each of said CSP substrates along said cutting streets by moving said chuck and a cutting means relatively to each other based on the stored position of said cutting streets of each of said CSP substrates, wherein

said frame has an opening at a central portion thereof, a mounting tape extending across said opening is stuck onto a back surface of said frame, and said CSP substrates are each stuck onto said mounting tape so as to be positioned in said opening of said frame,

the whole surface of said frame that mounts plural pieces of said CSP substrates is imaged by a whole-surface imaging means, and

the mounting position of each of said CSP substrates on said frame is recognized by analyzing the obtained image and is stored.

7. (Amended) A method of cutting CSP substrates comprising the steps of:

mounting plural CSP substrates on a single frame without overlapping them one upon the other, each CSP substrate having CSPs formed on plural rectangular regions thereof sectioned by cutting streets arranged in a form of a lattice;

recognizing a mounting position of each of said CSP substrates on said frame and storing the mounting positions in a storage means;

securing said frame mounting said plural CSP substrates onto a chuck;

imaging a surface of each of said CSP substrates by a precision imaging means, recognizing the positions of said cutting streets of each of said CSP substrates on said frame secured onto said chuck by analyzing the obtained image, and storing the position of each of said cutting streets in said storage means;

positioning said chuck, to which said frame is secured, relative to each other with respect to said precision imaging means based on the stored mounting position of each of said CSP substrates on said frame at a time of imaging the surface of each of said CSP substrates by said precision imaging means; and

cutting each of said CSP substrates along said cutting streets by moving said chuck and a cutting means relatively to each other based on the stored position of said cutting streets of each of said CSP substrates, wherein

said frame and a pick-up means are positioned relatively to each other based on the stored positions of the cutting streets of said CSP substrates, and

plural CSPs that have been cut are individually picked up from said frame by said pick-up means.